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DRG. NO. A - 2573 SH 1 REV. A

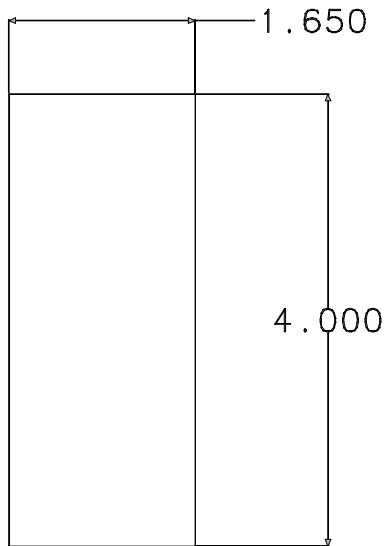
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Schematic Drawing: B - 2572  
Assembly Drawing: A - 2574

D

D

(inches)



Layer Order:



Board Characteristics:

1. Material: FR4.
2. Board Thickness: 0.062" +/- 0.008" (2.36 +/- .20mm).
3. Minimum Trace Width/Clearance: 0.006".
4. 1 oz Copper for top, bottom and power layers.  
1/2 oz Copper for embedded signal layers.
5. Solder plating; apply solder mask.
6. Silkscreen on Both Sides
7. Interlayer spacing : as specified.
8. FHS tolerances : +/- 0.003" unless specified otherwise.
9. Trace impedance: Zc = 55 Ohm +/- 10%.
10. Perform TDR tests and present test results.

AUX Card Drill Schedule (inches)

FHS	COUNT	PLATED	DRILL SYMBOL	COMMENT
.016	105	YES	○	
.035	80	YES	⊞	
.041	178	YES	⊕	
.042	20	YES	⊞	
.057	4	YES	⊖	
.106	4	NO	⊞	

B

B

A

A

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .004 .003 .004 DO NOT SCALE DRAWING	CONTRACT NO.		THE UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
	APPROVALS	DATE	TITLE		
	DRAWN M. Bogdan	8/31/05	QEBB - LVDS I/O - SAB Specification Drawing		
	CHECKED H. Sanders	8/31/05	SIZE B	FORM NO.	DRG. NO. A - 2573
FINISH	ISSUED			REV. A	
SIMILAR TO	ACT. WT	CALC WT	SCALE 1/2	SHEET 1 of 1	

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